

Data sheet acquired from Harris Semiconductor SCHS071B – Revised July 2003

CMOS Presettable Up/Down Counters

High-Voltage Types (20-Volt Rating)
CD4510B — — BCD Type
CD4516B — — Binary Type

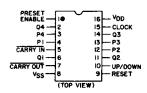
CD4510B Presettable BCD Up/Down Counter and the CD4516 Presettable Binary Up/Down Counter consist of four synchronously clocked D-type flip-flops (with a gating structure to provide T-type flip-flop capability) connected as counters. These counters can be cleared by a high level on the RESET line, and can be preset to any binary number present on the jam inputs by a high level on the PRESET ENABLE line. The CD4510B will count out of non-BCD counter states in a maximum of two clock pulses in the up mode, and a maximum of four clock pulses in the down mode.

If the CARRY-IN input is held low, the counter advances up or down on each positive-going clock transition. Synchronous cascading is accomplished by connecting all clock inputs in parallel and connecting the CARRY-OUT of a less significant stage to the CARRY-IN of a more significant stage.

The CD4510B and CD4516B can be cascaded in the ripple mode by connecting the CARRY-OUT to the clock of the next stage. If the UP/DOWN input changes during a terminal count, the CARRY-OUT must be gated with the clock, and the UP/DOWN input must change while the clock is high. This method provides a clean clock signal to the subsequent counting stage. (See Fig. 15).

These devices are similar to types MC14510 and MC14516.

The CD4510B and CD4516B types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4516B types also are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix).

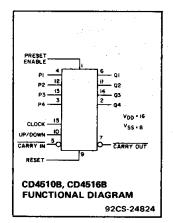


CD4510B, CD4516B
TERMINAL ASSIGNMENT

CD4510B, CD4516B Types

Features:

- Medium-speed operation -f_{CL} = 8 MHz typ. at 10 V
- Synchronous internal carry propagation
- Reset and Preset capability
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized symmetrical output characteristics
- Maximum input current of 1 μA at 18 V over full package temperature range;
 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range): 1 V at V_{DD} = 5 V
 2 V at V_{DD} = 10 V
 2.5 V at V_{DD} = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Up/Down difference counting
- Multistage synchronous counting
- Multistage ripple counting
- Synchronous frequency dividers

OPERATING CONDITIONS AT TA = 25°C, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

| Characteristic | V _{DD} | Min. | Max. | Units |
|---|-----------------|------|--------|-------|
| Supply Voltage Range (At TA = Full Package-Temperature Range) | | 3 | 18 | v |
| | 5 | 150 | | |
| Clock Pulse Width, t _W | 10 | 75 | - | ns |
| | 15 | 60 | - | |
| | 5 | _ | 2 | |
| Clock Input Frequency, f _{CL} | 10 | - | 4 | MHz |
| | 15 | - | 5.5 | |
| | 5 | 150 | _ | |
| Preset Enable or Reset Removal Time | 10 | 80 | - 1 | กร |
| | 15 | 60 | _ | |
| | 5 | _ | 15 | |
| Clock Rise and Fall Time, t _r CL, t _f CL* | 10 15 | _ | 5 5 | μs |
| | 5 | 130 | | |
| Carry-In Setup Time, t _S | 10 | 60 | - 1 | ns |
| | 15 | 45 | _ | |
| | 5 | 360 | _ | |
| Up-Down Setup Time, t _S | 10 | 160 | _ | ns |
| | 15 | 110 | _ | |
| | 5 | 220 | _ | |
| Preset Enable or Reset Pulse Width, tw | 10 | 100 | _ } | ns |
| | 15 | 75 | _ | |

[•]Time required after the falling edge of the reset or preset enable inputs before the rising edge of the clock will trigger the counter (similar to setup time).

^{*}If more than one unit is cascaded in the parallel clocked application, t_rCL should be made less than or equal to the sum of the fixed propagation delay at 15 pF and the transition time of the carry output driving stage for the estimated capacitive load.

| MAXIMUM RATINGS, Absolute-Maximum Values: | |
|---|--------------------------------------|
| DC SUPPLY-VOLTAGE RANGE, (V _{DD}) | |
| Voltages referenced to VSS Terminal) | 0.5V to +20V |
| INPUT VOLTAGE RANGE, ALL INPUTS | 0.5V to V _{DD} +0.5V |
| DC INPUT CURRENT, ANY ONE INPUT | ±10mA |
| POWER DISSIPATION PER PACKAGE (PD): | |
| For T _A = -55°C to +100°C | 500mW |
| | _ |
| For TA = +100°C to +125°C | Derate Linearity at 12mW/°C to 200mW |
| For T _A = +100°C to +125°C DEVICE DISSIPATION PER OUTPUT TRANSISTOR | Derate Linearity at 12mW/°C to 200mW |
| • • | |
| DEVICE DISSIPATION PER OUTPUT TRANSISTOR | Types)100mW |
| DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package OPERATING-TEMPERATURE RANGE (T _A) | 1Types)100mW 55°C to +125°C |
| DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package) | 1Types)100mW 55°C to +125°C |

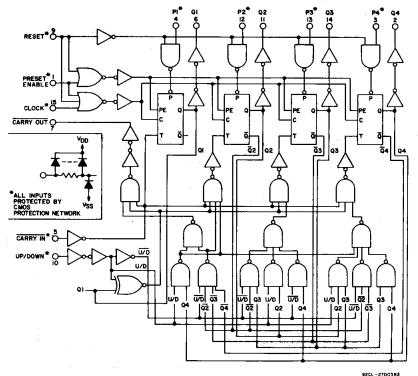


Fig.3 — Logic Diagram for CD45108.

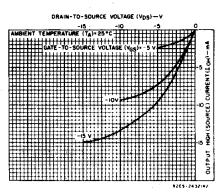


Fig.5 – Minimum output high (source) current characteristics.

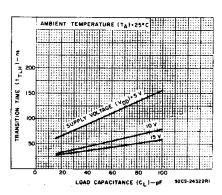


Fig.6 — Typical transition time vs. load capacitance.

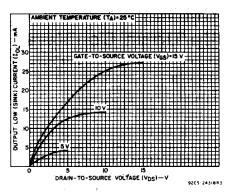


Fig.1 - Typical output low (sink) current characteristics.

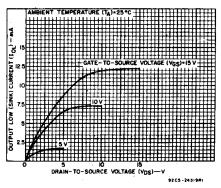


Fig. 2 – Minimum output low (sink) current characteristics.

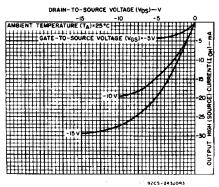


Fig.4 - Typical output high (source) current characteristics.

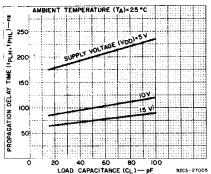
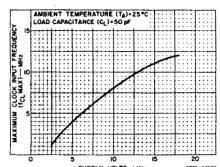


Fig. 7 — Typical propagation delay time vs. load capacitance for clock-to-Q outputs.

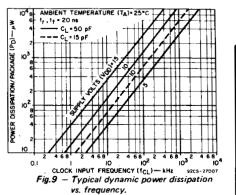
STATIC ELECTRICAL CHARACTERISTICS

| CHARACTER- | COND | is | LIMITS AT INDICATED TEMPERATURES (°C) | | | | | | UNITS | | |
|------------------------------------|----------|------|---------------------------------------|-------|------------|-------|-------|-------|-------------------|------|------|
| ISTIC | Vo | VIN | VDD | | | | | | +25 | | UNIT |
| | (v) | (V) | (V) | -55 | -40 | +85 | +125 | Min. | Тур. | Max. | 1 |
| Quiescent Device | - | 0,5 | 5 | 5 | 5 | 150 | 150 | _ | 0.04 | 5 | |
| Current, | _ | 0,10 | 10 | 10 | 10 | 300 | 300 | - | .0.04 | 10 | μΑ |
| IDD Max. | _ | 0,15 | 15 | 20 | 20 | 600 | 600 | - | 0.04 | 20 | μΑ. |
| | - | 0,20 | 20 | -100 | 100 | 3000 | 3000 | - | 0.08 | 100 | ŀ |
| Output Low | 0.4 | 0,5 | 5 | 0.64 | 0.61 | 0.42 | 0.36 | 0.51 | 1 | - | |
| (Sink) Current | 0.5 | 0,10 | 10 | 1.6 | 1.5 | 1.1 | 0.9 | 1.3 | 2.6 | - | |
| IOL Min. | 1.5 | 0,15 | 15 | 4.2 | 4 | 2.8 | 2.4 | 3.4 | 6.8 | | 1 |
| Output High | 4.6 | 0,5 | 5 | -0.64 | -0.61 | -0.42 | -0.36 | -0.51 | -1 | - | mA |
| (Source) | 2.5 | 0,5 | 5 | -2 | -1.8 | -1.3 | -1.15 | -1.6 | -3.2 | - | |
| Current, IOH Min. | 9,5 | 0,10 | 10 | -1.6 | ~1.5 | -1.1 | -0.9 | -1.3 | -2.6 | - | |
| | 13.5 | 0,15 | 15 | 4,2 | -4 | -2.8 | -2.4 | -3.4 | -6.8 | - | |
| Output Voltage: | - | 0,5 | 5 | 0.05 | | | | - | . 0 | 0.05 | |
| Low-Level, VOL Max. | _ | 0,10 | 10 | | 0.05 | | | | 0 | 0.05 | |
| AOF Max. | | 0,15 | 15 | 0.05 | | | | - | 0 | 0.05 | v |
| Output Voltage: | | 0,5 | 5 | | 4 | .95 | | 4.95 | . 5 | - | ľ |
| High-Level, | | 0,10 | 10 | | 9 | .95 | | 9.95 | 10 | - | |
| VOH Min. | _ | 0,15 | 15 | | 14 | .95 | | 14.95 | 15 | - | |
| Input Low | 0.5, 4.5 | _ | 5 | | 1 | .5 | | _ | _ | 1.5 | |
| Voltage, | 1, 9 | _ | 10 | | | 3 | | _ | | 3 | |
| VIL Max. | 1.5,13.5 | - | 15 | | | 4 | | - | | 4 | v |
| Input High Voltage, VIH Min. | 0.5, 4.5 | | 5 | | 3 | 3.5 | | 3.5 | - | _ | V |
| | 1, 9 | | 10 | | | 7 | | 7 | _ | _ | |
| | 1.5,13.5 | - | 15 | | | 1 | | 11 | _ | _ | |
| Input Current IIN Max. | - | 0,18 | 18 | ±0.1 | ±0.1 | ±1 | ±1 | _ | ±10 ⁻⁵ | ±0.1 | μΑ |



SUPPLY VOLTS -- VDD 92CS-27006

Fig. 8 -- Typical maximum clock input frequency vs. supply voltage.



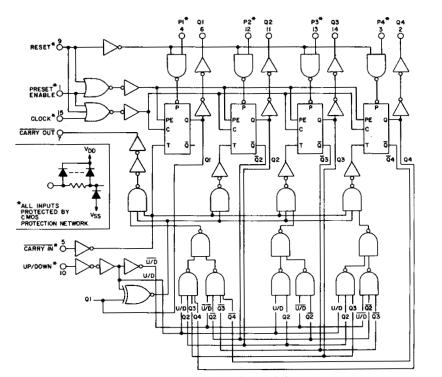


Fig. 10 - Logic Diagram for CD4516B.

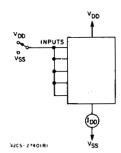


Fig. 11 — Quiescent-device-current test circuit.

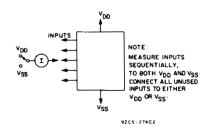


Fig. 12 - Input-current test circuit.

92CL - 27004R2

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_{A}$ = 25°C, C $_{L}$ = 50 pF, Input t $_{r}$, t $_{f}$ = 20 ns, R $_{L}$ = 200 k Ω

| Characteristic | Conditions VDD (V) | Al Min. | Limits II Package Typ. | s Max. | Units |
|---|--------------------|----------------|------------------------------|-------------------|--|
| Propagation Delay Time (tpHL, tpLH): | | 1,4,11,1 | 190. | IVIAX. | |
| Clock-to-Q Output (See Fig. 10) | 5 10 15 | _ _ | 200 100 75 | 400 200 150 | ns |
| Preset or Reset-to-Q Output | 5 10 15 | | 210 105 80 | 420 210 160 | ns |
| Clock-to-Carry Out | 5 10 15 | - - - | 240 120 90 | 480 240 180 | ns |
| Carry-In-to-Carry Out | 5 10 15 | - - | 125 60 50 | 250 120 100 | ns |
| Preset or Reset-to-Carry Out | 5 10 15 | - - - | 320 160 125 | 640 320 250 | ns |
| Transition Time (t _{THL} , t _{TLH}) (See Fig. 9) | 5 10 15 | _ _ _ | 100 50 40 | 200 100 80 | ns |
| Max. Clock Input Frequency (f _{CL}) | 5 10 15 | 2 4 5.5 | 4 8 11 | - - - | MHz |
| Input Capacitance (C _{IN}) | | - | 5 | 7.5 | pF |
| Set-up Time, t _S Preset Enable to J _n | 5 10 15 | 25 10 10 | 12 6 5 | <u>-</u> | |
| Hold times, t _H Clock to Carry-In | 5 10 15 | 60 30 30 | 30 4 1 | | ns |
| Clock to Up/Down | 5 10 15 | 30 30 30 | 10 4 5 | | |
| Preset Enable to J _n | 5 10 15 | 70 40 40 | 35 20 20 | | |

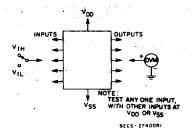
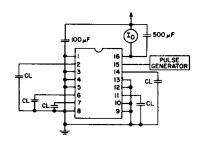


Fig. 13 - Input-voltage test circuit.



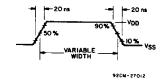
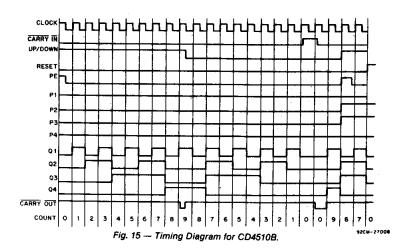


Fig. 14 — Power-dissipation test circuit and input waveform,



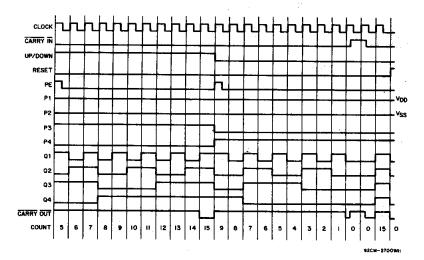
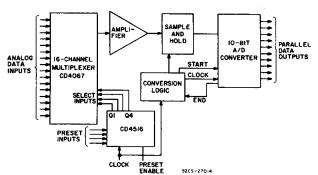


Fig. 16 — Timing diagram for CD4516B.

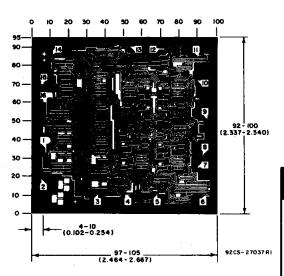


This acquisition system can be operated in the random access mode by jamming in the channel number at the present inputs, or in the sequential mode by clocking the CD4516B.

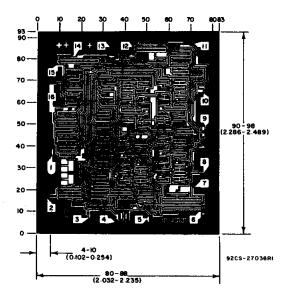
Fig. 17 — Typical 16-channel, 10-bit data acquisition system.

| CL | lö | U/D | PΕ | R | ACTION | | | |
|----------------|----|-----|----|---|------------|--|--|--|
| 'X | 1 | Х | 0 | ٥ | NO COUNT | | | |
| 5 | 0 | . 1 | ٥ | ٥ | COUNT UP | | | |
| 7 | 0 | 0 | Ó | 0 | COUNT DOWN | | | |
| X | X | X | 1 | | PRESET | | | |
| X | X | X | X | 1 | RESET | | | |
| Y - DON'T CARE | | | | | | | | |

TRUTH TABLE

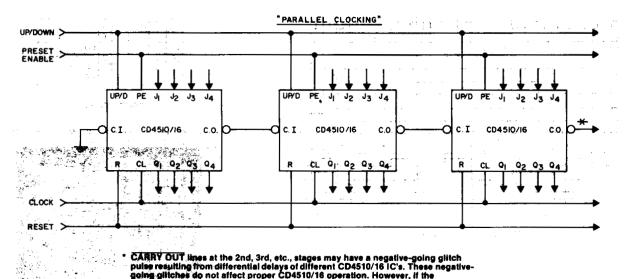


Dimensions and Pad Layout for CD45108H.

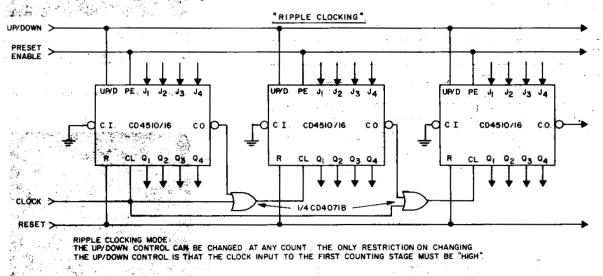


Dimensions and Pad Layout for CD4516BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .



* CARRY OUT lines at the 2nd, 3rd, etc., stages may have a negative-going glitch pulse resulting from differential delays of different CD4510/16 IC's. These negative-going glitches do not affect proper CD4510/16 operation. However, if the CARRY OUT signals are used to trigger other edge-sensitive logic devices, such as FF's or counters, the CARRY OUT signals should be gated with the clock signal using a 2-input OR gate such as CD4071B.



RIPPLE CLOCKING MODE:
THE UP/DOWN CONTROL CAR BE CHANGED AT ANY COUNT. THE ONLY RESTRICTION ON CHANGING
THE UP/DOWN CONTROL IS THAT THE CLOCK INPUT TO THE FIRST COUNTING STAGE MUST BE "HIGH".

For exacading counters operating in a fixed up-count or down-count mode, the OR gallet are military in the CL input at the large with CI grounded.

92CL-17194R5

Fig. 18 — Cascading counter packages.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| CD4510BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4510BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4510BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4510BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4510BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4510BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4510BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4510BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4516BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4516BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4516BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4516BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4516BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| All ulmensions are nominal | | | | | | | | | | | | |
|----------------------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
| CD4510BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4510BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4516BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4516BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4510BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4510BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| CD4516BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4516BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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